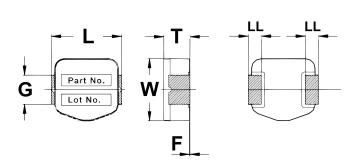




Aliases (UPIE0630L2R200) KEMET, MPLCG, Metal Composite, 20%, 2,200 nH, 0630(2826)



| General Information | |
|---------------------|-------------------------------------|
| Series | MPLCG |
| Style | SMD Molded |
| Core | Metal Composite |
| Description | Shielded, Surface Mount Inductor |
| Features | Large Current Inductors |
| RoHS | Yes |
| Miscellaneous | 40 (K) Temperature Rise Max. |

Click here for the 3D model.

| Dimensions | |
|------------|----------------|
| Chip Size | 0630(2826) |
| L | 7.5mm MAX |
| W | 6.7mm +/-0.2mm |
| Т | 3mm MAX |
| G | 3.2mm +/-0.2mm |

| Packaging Specifications | |
|--------------------------|------------|
| Typical Component Weight | 650 mg |
| Packaging | T&R, 380mm |
| Packaging Quantity | 2000 |

| Specifications | |
|----------------------|--|
| Inductance | 2.2 uH (0.1 MHz) |
| Inductance Tolerance | 20% |
| Inductance | 2,200 nH |
| Rated Current | 8.2 A (Irms, 40C Rise By Self Heating) |
| Saturation Current | 7.8 A (Isat, 20% Drop In Inductance) |
| Temperature Range | -40/+125°C |
| Rated Temperature | 120°C |
| Shielded | Yes |
| Current | 7.8 A (Isat, 20% Drop In Inductance), 8.2 A (Irms, 40C Rise By Self Heating) |
| DC Resistance | 19 mOhms |
| DC Resistance | 19 mOhms |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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